

Description

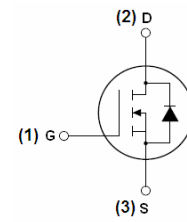
The RST3019AS uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

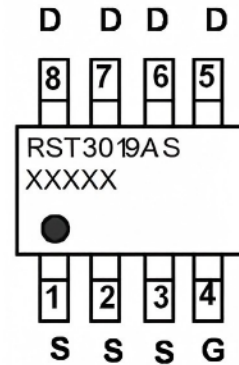
- $V_{DS} = 30V, I_D = 19A$
 $R_{DS(ON)} < 6.2m\Omega @ V_{GS}=10V$
 $R_{DS(ON)} < 9m\Omega @ V_{GS}=4.5V$
- High density cell design for ultra low R_{dson}
- Fully characterized Avalanche voltage and current

Application

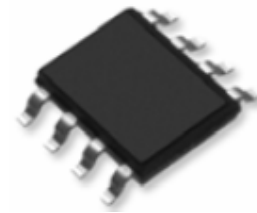
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Schematic diagram



Marking and pin Assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
RST3019AS	RST3019AS	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	19	A
Drain Current-Continuous($T_A=100^\circ\text{C}$)	$I_D (100^\circ\text{C})$	13.5	A
Pulsed Drain Current	I_{DM}	76	A
Maximum Power Dissipation	P_D	3	W
Single pulse avalanche energy ^(Note 5)	E_{AS}	210	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$
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Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

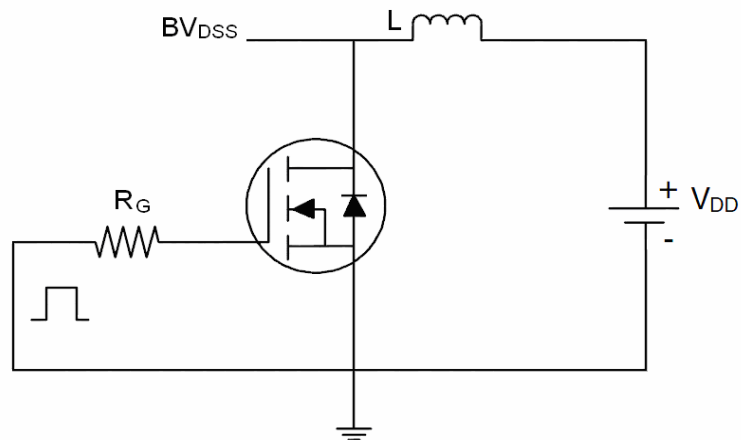
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.7	1.1	1.4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A	-	4.9	6.2	mΩ
		V _{GS} =4.5V, I _D =10A	-	6.9	9	
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =12A	5	-	-	S
Dynamic Characteristics ^(Note4)						
Input Capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	2077	-	PF
Output Capacitance	C _{oss}		-	300	-	PF
Reverse Transfer Capacitance	C _{rss}		-	249.7	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V,I _D =10A V _{GS} =10V,R _{GEN} =2.7Ω	-	20	-	nS
Turn-on Rise Time	t _r		-	15	-	nS
Turn-Off Delay Time	t _{d(off)}		-	60	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Q _g	V _{DS} =15V,I _D =10A, V _{GS} =10V	-	47.6	-	nC
Gate-Source Charge	Q _{gs}		-	4.9	-	nC
Gate-Drain Charge	Q _{gd}		-	10.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-	-	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	19	A

Notes:

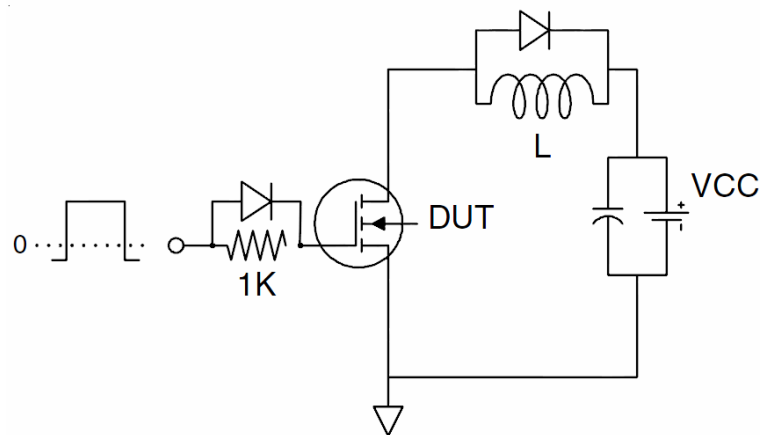
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. E_{AS} condition: $T_J=25^{\circ}\text{C}, V_{DD}=15V, V_G=10V, L=0.5\text{mH}, R_g=25\Omega$

Test Circuit

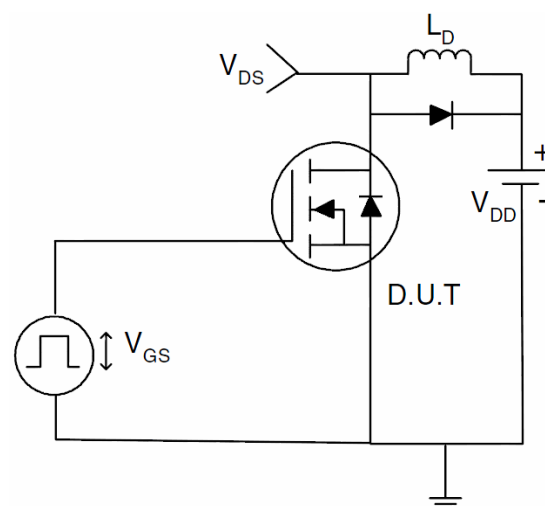
1) E_{AS} Test Circuits

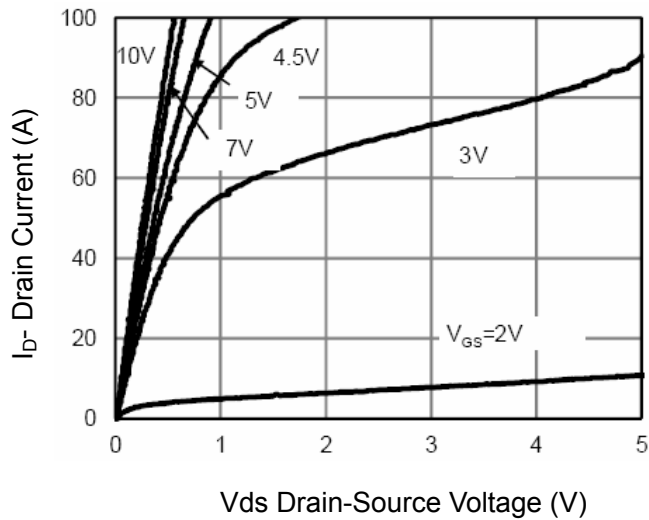
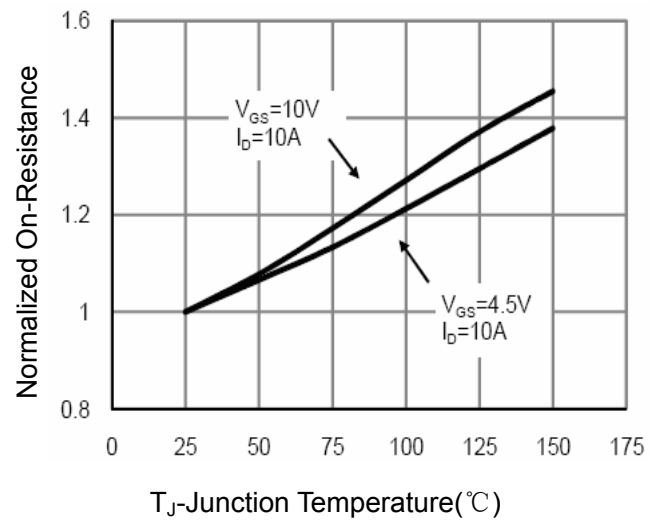
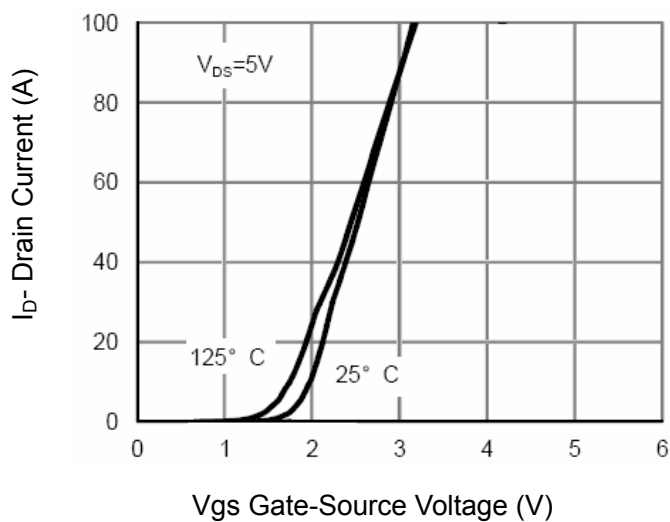
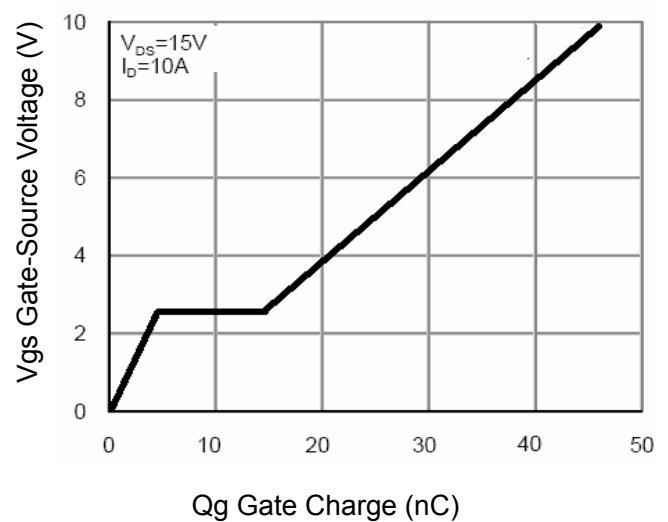
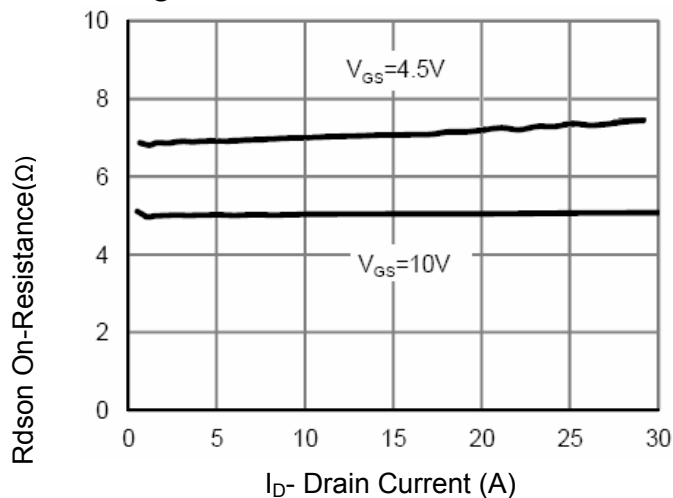
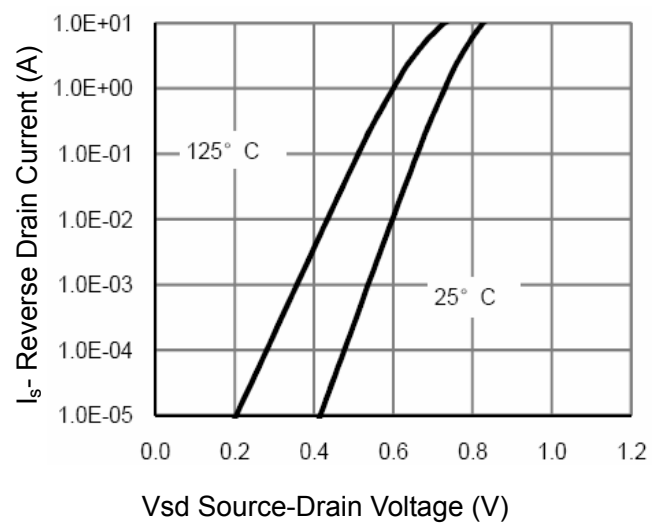


2) Gate Charge Test Circuit



3) Switch Time Test Circuit



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Typical Electrical and Thermal Characteristics (Curves)

Figure 1 Output Characteristics

Figure 4 Rdson-Junction Temperature

Figure 2 Transfer Characteristics

Figure 5 Gate Charge

Figure 3 Rdson- Drain Current

Figure 6 Source- Drain Diode Forward

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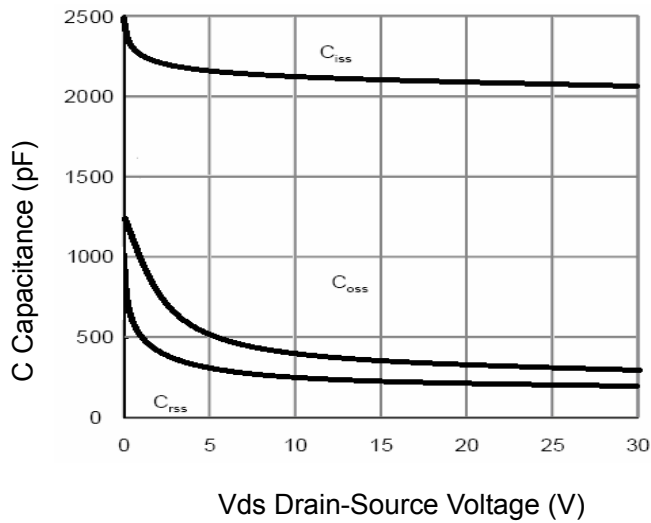


Figure 7 Capacitance vs Vds

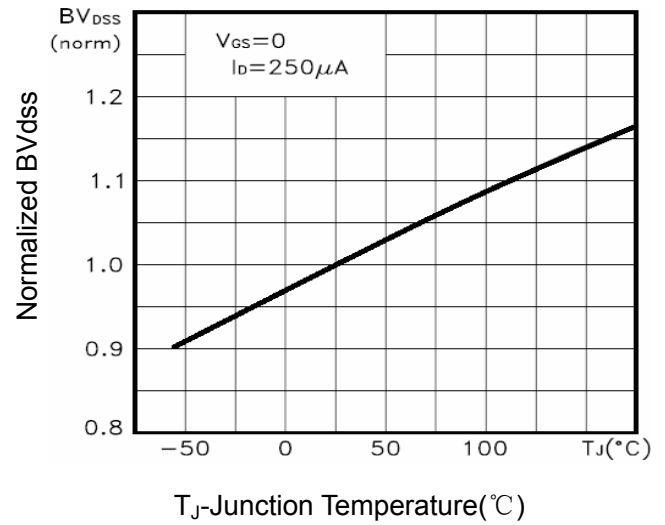


Figure 9 BV_{DSS} vs Junction Temperature

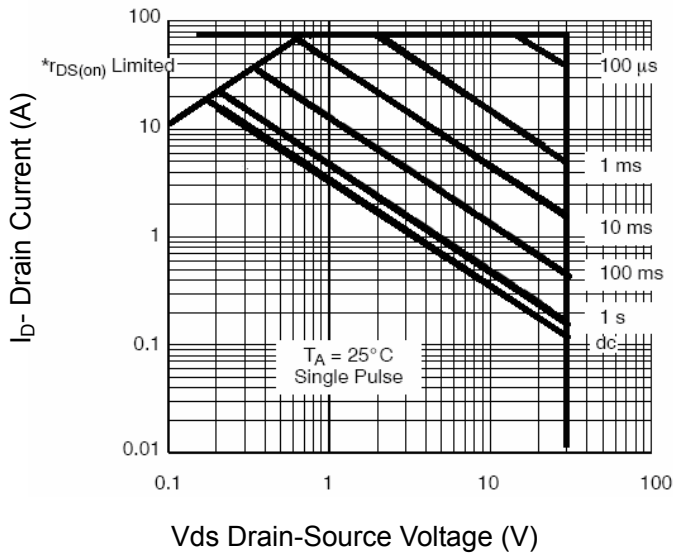


Figure 8 Safe Operation Area

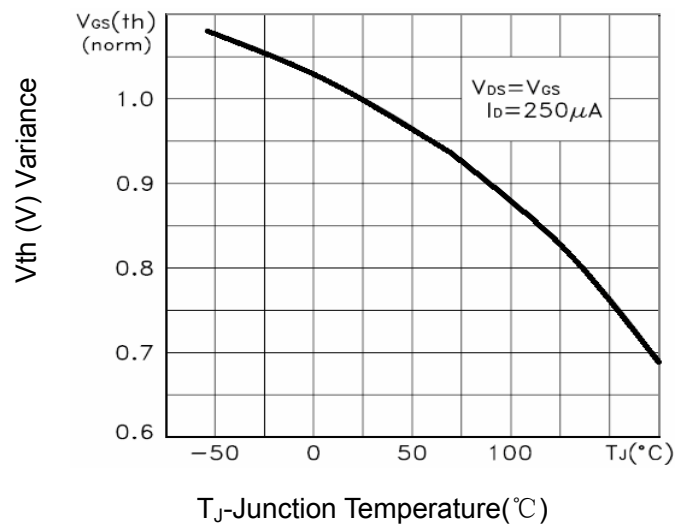


Figure 10 V_{GS(th)} vs Junction Temperature

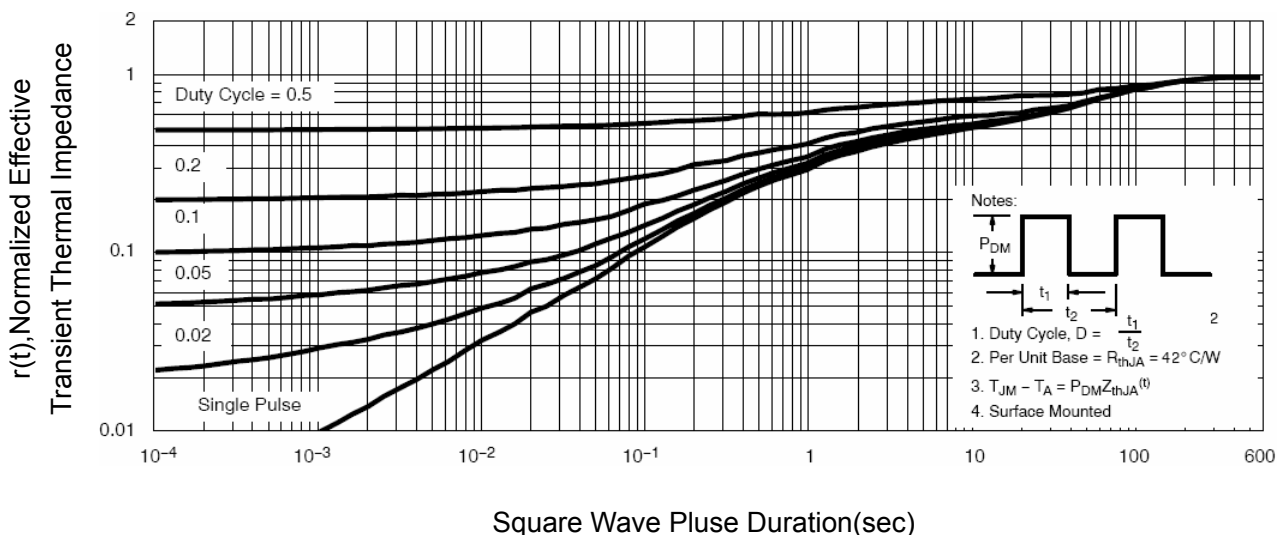
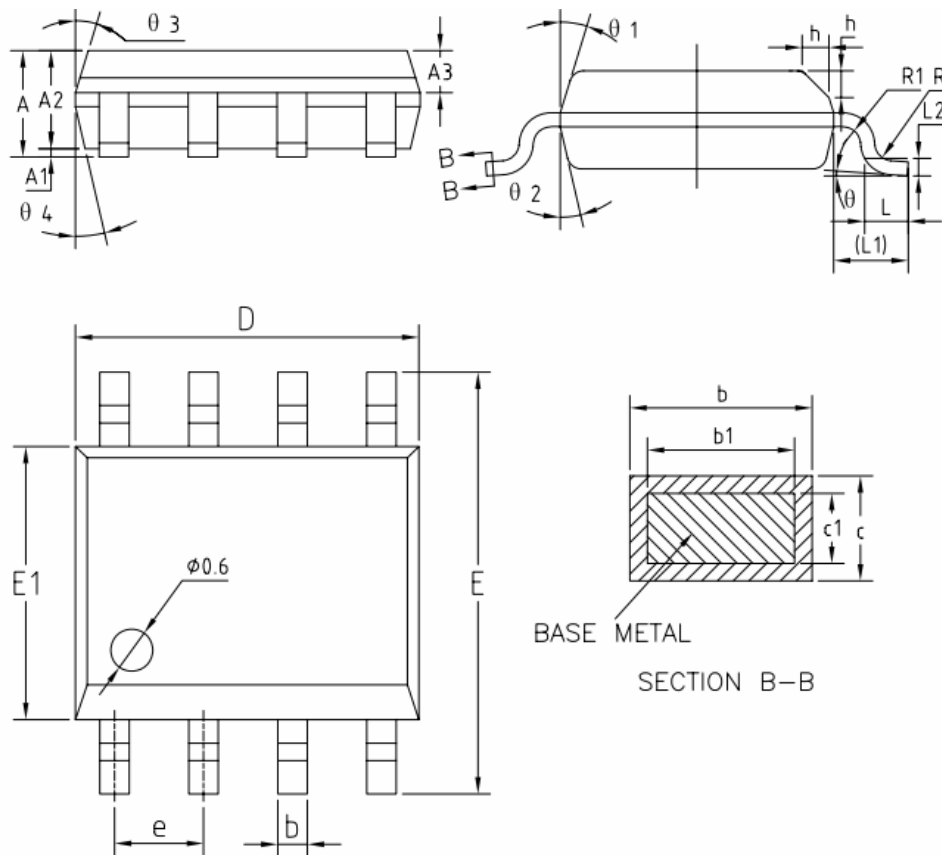


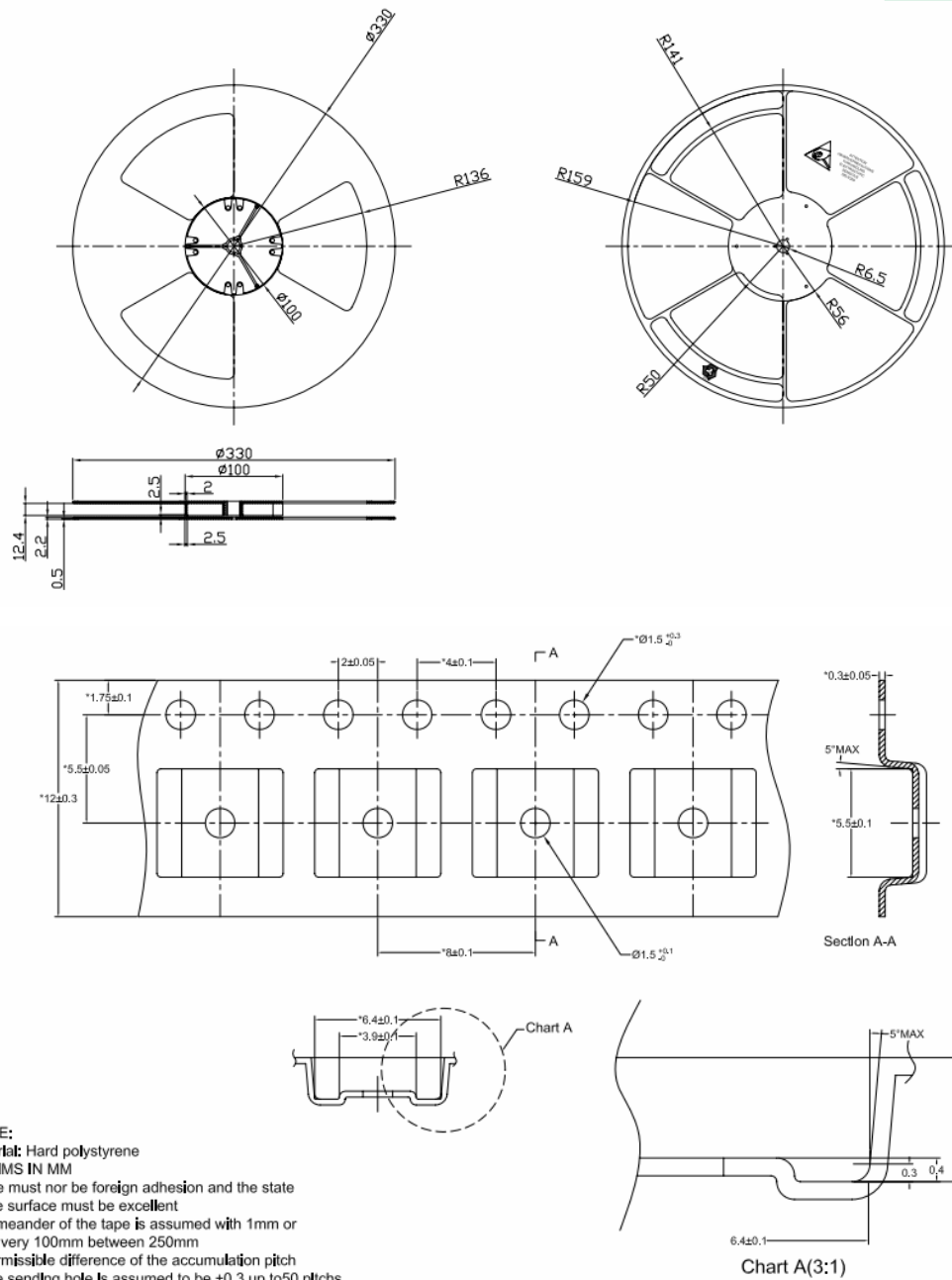
Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information
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COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.15	0.25
A2	1.25	1.40	1.65
A3	0.50	0.60	0.70
b	0.38	—	0.51
b1	0.37	0.42	0.47
c	0.18	—	0.25
c1	0.17	0.20	0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.17	1.27	1.37
L	0.45	0.60	0.80
L1	1.04REF		
L2	0.25BSC		
R	0.07	—	—
R1	0.07	—	—
h	0.30	0.40	0.50
1	0°	—	8°
1	15°	17°	19°
2	11°	13°	15°
3	15°	17°	19°
4	11°	13°	15°

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NOTICE:

1. Material: Hard polystyrene
2. All DIMS IN MM
3. There must not be foreign adhesion and the state of the surface must be excellent
4. The meander of the tape is assumed with 1mm or less very 100mm between 250mm
5. A permissible difference of the accumulation pitch of the sending hole is assumed to be ± 0.3 up to 50 pitches
6. Corner R=0,3max
7. Surface resistance $1 \times 10^5 \leq R_s \leq 1 \times 10^{12}$ OHMS/SQ
8. Key size with ""

